



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 8, 2007

Applicants: Uwe HOFMANN et al

Title: LEAD-FREE COPPER ALLOY AND A METHOD OF MANUFACTURE

Serial No.: 10/786 470

Group: 1742

Confirmation No.: 9330

Filed: February 25, 2004

Examiner: Ip

Atty. Docket No.: 5200.P0062US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

[] Applicant claims small entity status. See 37 CFR 1.27.

[] The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Total Claims	(18 - 20 = 0)		x	\$ 50.00	x	\$ 25.00
Indep. Claims	(1 - 3 = 0)		x	\$200.00	x	\$100.00
[] Multiple Dep. Claim			+	\$360.00	+	\$180.00
* * * TOTAL FILING FEE * * *						\$ 0.00

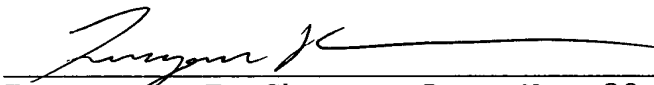
[X] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by one month. The extension fee is: \$120.00.

[X] A Check for \$120.00 is enclosed to cover fees.

[X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

IN DUPLICATE

TFC/smd

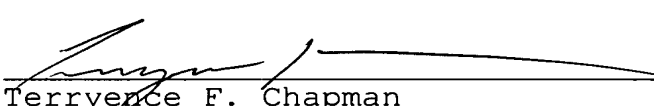

Terryence F. Chapman Reg. No. 32 549

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in a hard copy envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 8, 2007.

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Terryence F. Chapman